



Numerical Heat Transfer

Chapter 13 Application examples of fluent for basic flow and heat transfer problem



Instructor Wen-Quan Tao; Qinlong Ren; Li Chen

CFD-NHT-EHT Center Key Laboratory of Thermo-Fluid Science & Engineering Xi'an Jiaotong University Xi'an, 2018-Dec.-19





数值传热学



主讲 陶文铨 辅讲 任秦龙,陈 黎 西安交通大学能源与动力工程学院 热流科学与工程教育部重点实验室 2018年12月19日, 西安



13.1 Heat transfer with source term

13.2 Unsteady cooling process of a steel ball

13.3 Lid-driven flow and heat transfer

13.4 Flow and heat transfer in a micro-channel

13.5 Flow and heat transfer in chip cooling

13.6 Phase change material melting with fins



13.1 有内热源的导热问题 导热问题 13.2 非稳态圆球冷却问题 13.3 顶盖驱动流动换热问题 混合对流问题 13.4 微通道内流动换热问题 13.5 芯片冷却流动换热问题 微通道问题 13.6 肋片强化相变材料融化 相变传热



Example 4: Fluid-solid interface



This wall type has fluid zone and solid zone on each side. This wall is called a "two-sided-wall".

When such kind wall is read into Fluent, a "shadow" (影子) zone is automatically created.





There are three options for the temperature boundary conditions of such "two-sided-wall".

Thermal Conditions



- Heat flux
- Temperature

Coupled

If you choose "Coupled", no additional information is required. The solver will calculate heat transfer directly from the solution of adjacent cells. Such wall is not a boundary. 》 西安交通大學



Its shadow created by Fluent



Pressure outlet boundary condition

Pressure Outlet	x
Zone Name	
out	
Momentum Thermal Radiation Species DPM Multiphase UDS	
Gauge Pressure (pascal) 0 constant	•
Backflow Direction Specification Method Normal to Boundary	-
Average Pressure Specification	
Target Mass Flow Rate	
OK Cancel Help	

Gauge Pressure (表压)



For pressure outlet boundary condition, Fluent asks you to input a Backflow (回流) Total Temperature. However, it will play a role only if there is backflow. There is no information provided by Fluent Help File about what is the actual boundary condition for heat transfer.

Pressure Outlet	×
Zone Name	
wall	
Momentum Thermal Radiation	Species DPM Multiphase UDS
Backflow Total Temperature (k) 3	00 constant 👻
Backflov	w Total Temperature
	OK Cancel Help





The problem has been asked by many users.

Someone indicate online that the actual value of temperature is calculated using the value of last time step, or by interpolating methods from values of neighboring nodes.







Pressure in Fluent

- Atmospheric pressure (大气压)
- Gauge pressure (表压): the difference between the true pressure and the Atmospheric pressure.
- Absolute pressure (真实压力): the true pressure
 - = Atmospheric pressure + Gauge pressure
- **Operating pressure (操作压力)**: the reference pressure (参考压力)
- In our teaching code, a reference pressure point is defined.





Pressure in Fluent

- Absolute pressure (真实压力): the true pressure
 - = **Reference Pressure** + **Relative Pressure**
- Static pressure (静压): the difference between true pressure and operating pressure.
- The same as relative pressure.
- Dynamic pressure (动压): calculated by $0.5\rho U^2$
- Is related to the velocity.
- Total pressure (总压):
 - = Static pressure + dynamic pressure





13.5 Flow and heat transfer in chip cooling

芯片冷却流动换热问题

Focus: compared with previous examples, this example is a relatively realistic problem. The domain of this Example contains fluid, board (电路板) and chip (芯片).





13.5 Flow and heat transfer in chip cooling

Known: Steady laminar flow and convective heat transfer around a board on top of which is a chip with source term. The domain and size is shown in Fig. 1. The boundary conditions are as follows:

■ Inlet: *u*---0.5m/s (constant)

Т---298К

- Pressure outlet: Gauge pressure (表压):0 Pa.
- Top and bottom boundary: 3rd boundary condition
 Heat transfer coefficient: *H*=1.5 W/(m²K);
 Free stream temperature: *T_f*=298K.



CFD-NHT-EHT

- Chip-- a constant source term, 904055 W/m³
- Front surface and back surface---symmetry





Find: Temperature distribution in the domain.

Solution:

$$\frac{\partial u}{\partial x} + \frac{\partial v}{\partial x} = 0$$

$$u\frac{\partial u}{\partial x} + v\frac{\partial u}{\partial y} = -\frac{1}{\rho_f}\frac{\partial p}{\partial x} + \frac{\mu_f}{\rho_f}\left(\frac{\partial^2 u}{\partial x^2} + \frac{\partial^2 u}{\partial y^2}\right)$$

$$u\frac{\partial v}{\partial x} + v\frac{\partial v}{\partial y} = -\frac{1}{\rho_f}\frac{\partial p}{\partial y} + \frac{\mu_f}{\rho_f}\left(\frac{\partial^2 v}{\partial x^2} + \frac{\partial^2 v}{\partial y^2}\right)$$

$$\frac{\partial(\rho_f C_{pf} u_f T_f)}{\partial x} + \frac{\partial(\rho_f C_{pf} v_f T_f)}{\partial y} = \lambda_f \left(\frac{\partial^2 T_f}{\partial x^2} + \frac{\partial^2 T_f}{\partial y^2} \right)$$

$$0 = \lambda_s \left(\frac{\partial^2 T_s}{\partial x^2} + \frac{\partial^2 T_s}{\partial y^2} \right) + s$$





13.5.1 Start the Fluent software

Fluent Launcher	- 0	\times
ANSYS	Fluent Lau	ncher
Dimension 2D 3D Display Options Display Mesh After Reading Embed Graphics Windows Workbench Color Scheme	Options Double Precision Meshing Mode Processing Options Serial Prarallel	
Show More Options <u> D</u> K <u> D</u> efault	<u>C</u> ancel <u>H</u> elp ▼	

Choose 3-Dimension
 Choose display options
 Choose Serial
 processing option





1st step: Read and check the mesh

The mesh is generated by pre-processing software such as ICEM and GAMBIT. The document is with suffix (后缀名) "xx.msh"



1st step: Read and check the mesh

Mesh→Check

Check the quality and topological information of the mesh

```
Mesh Check
Domain Extents:
  x-coordinate: min (m) = 0.000000e+00, max (m) = 1.651000e-01
  y-coordinate: min (m) = 0.000000e+00, max (m) = 2.794000e-02
  z-coordinate: min (m) = -2.540000e-07, max (m) = 1.270000e-02
Unlume statistics:
  minimum volume (m3): 1.119834e-09
  maximum volume (m3): 7.845747e-09
    total volume (m3): 5.858386e-05
Face area statistics:
  minimum face area (m2): 8.370037e-07
  maximum face area (m2): 4.194085e-06
Checking mesh.....
Done.
```



2st step: Scale the domain size

General→Scale

3st step: Choose the physicochemical model

Re number is calculated to determine the fluid state (laminar or turbulent)

$$\operatorname{Re}=\frac{\rho u l}{\mu}$$

The density of air is 1.29Kg/m³; the inlet velocity is 0.5m/s, characteristic length is about 2cm, and kinetic viscosity of air is 1.7894E-05. *Re* is 720 and thus flow is laminar.

















Step 4: Define the material properties

If you calculate the density using the ideal gas law, the solver will compute the density according to ideal gas state equation.



Define a new material as Chip:

density 1000 kg/m³, Cp 500 J/(kg K) and thermal conductivity 1 W/(mK)

Define a new material as Board:

density 2000 kg/m³, Cp 600 J/(kg K) and thermal conductivity 0.1 W/(mK) 22/32



Step 5: Define zone condition

Assign different regions with the corresponding materials.

For the chip, there is a source term with value of 904055 W/m³

💶 Solid				
Zone Name cont-solid-chip]			
	Energy sources			×
Material Name chip -	source	term	Number of Energy sources	
Mesh Motion Fixed Values Reference Frame Mesh Motion Source Terr	1. (w/m3) 904055		constant	•
Energy 1 source Edit				23/32

Inlet: *u* and *T* are specified.

Velocity Inlet
Zone Name
inlet
Momentum Thermal Radiation Species DPM Multiphase UDS
Velocity Specification Method Magnitude, Normal to Boundary
u=0.5 Reference Frame Absolute
Velocity Inlet
Zone Name
inlet
Momentum Thermal Radiation Species DPM Multiphase UDS
Temperature (k) 298 $T=298$ constant \checkmark



Outlet: pressure outlet, Gauge pressure as 0.

Pressure Outlet	×
Zone Name	
outlet	
Momentum Thermal Radiation Species DPM	Multiphase UDS
Gauge Pressure (pascal)	constant
Backflow Direction Specification Method Normal to Bo	undary 👻
Radial Equilibrium Pressure Distribution	
Average Pressure Specification	
Target Mass Flow Rate	
OK	
	25/32

Top and bottom wall: convective boundary condition

💶 Wall				×
Zone Name				
wall-board-bottom				
Adjacent Cell Zone				
cont-solid-board				
Momentum Thermal Rad	liation Species DPM Multiphase	JDS Wall Film		
Thermal Conditions				
🔘 Heat Flux	Heat Transfer Coefficient (w/n	n2-k) 1.5	constant	•
 Temperature Convection 	Free Stream Temperatur	e (k) 298	constant	
Radiation		250		•
 Mixed via System Coupling 		Wall Thic	kness (in) 0	P
Material Name	Heat Generation Rate (w	/m3) 0	constant	•
aluminum	← Edit	L	Shell Conduction	Define
	OK Can	cel Help		

- For the front and back boundaries, keep the default set up of Symmetry.
- For all the other "two-sidewalls" boundaries in the domain, keep the default set up for thermal conditions, namely "Coupled". For details of "Coupled" and "uncoupled" conditions, refer to Example 4 in Chapter 13.







There are many two-sided-wall in this Example.







7st step: Define the solution

For algorithm and schemes, keep it as default. For more details of this step, one can refer to Example 1 of Chapter 13.

Solution Methods		
Pressure-Velocity Coupling		
Scheme		
SIMPLE	-	
Spatial Discretization		
Gradient		
Least Squares Cell Based	•	
Pressure		
Second Order		
Momentum		
Second Order Upwind		
Energy		
Second Order Upwind		
		-
Transient Formulation		
	-	
Non-Iterative Time Advancement		
Frozen Flux Formulation		

Algorithm: simple

Gradient: Least Square Cell Based

Pressure: second order

Momentum: second order upwind

Energy: second order Upwind



7st step: Define the solution

For under-relaxation factor, keep it default. For more details, refer to Example 1.

8st step: Initialization

Use the standard initialization, for more details of Hybrid initialization, refer to Example 1.

Step 9: Run the simulation

Step 10: Post-processing results



Static Temperature(K) of back boundary









同舟共济 渡彼岸!

People in the same boat help each other to cross to the other bank, where....





Numerical Heat Transfer

Chapter 13 Application examples of fluent for basic flow and heat transfer problem



Instructor Wen-Quan Tao; Qinlong Ren; Li Chen

CFD-NHT-EHT Center Key Laboratory of Thermo-Fluid Science & Engineering Xi'an Jiaotong University Xi'an, 2018-Dec.-19





数值传热学



主讲 陶文铨 辅讲 任秦龙,陈 鯬 西安交通大学能源与动力工程学院 热流科学与工程教育部重点实验室 2018年12月19日, 西安

2/13



13.1 Heat transfer with source term

13.2 Unsteady cooling process of a steel ball

13.3 Lid-driven flow and heat transfer

13.4 Flow and heat transfer in a micro-channel

13.5 Flow and heat transfer in chip cooling

13.6 Phase change material melting with fins



13.1 有内热源的导热问题 导热问题 13.2 非稳态圆球冷却问题 13.3 顶盖驱动流动换热问题 混合对流问题 13.4 微通道内流动换热问题 13.5 芯片冷却流动换热问题 微通道问题 13.6 肋片强化相变材料融化 相变传热





Review



Patching (修补) Values in Selected Cells



Domain

Sub-region need to Patch

- **1.** Define the sub-region
- 2. Use Patch to specify related variables.



CFD-NHT-EHT

For transient problem you have to

time stepping method, time step size, the max iteration per time step









For fully implicit scheme, Δt does not affect stability, but will affect the accuracy of the simulation results.

The following way is recommended by Fluent to set ∆t:

At each time step, the ideal iteration number is 5 10.

2. If Fluent needs more inner iteration step (>10) for convergence at each time step, Δt is too large.

3. If Fluent needs only a few iteration steps, Δt is too





13.6 Phase change material melting with fins

肋片强化相变材料融化传热问题

Focus: compared with previous examples, the focus of this example is solid-liquid phase change heat transfer.



13.6 Phase change material melting with fins

Known: Paraffin RT50 is used as the phase change material, and internal copper fins are used to enhance the solid-liquid phase change inside the 3D square cavity.

Property Copper RT50 ρ [kg/m³] 8954 880 C _p [J/kg·K] 383 2000 k [W/m·K] 400 0.2
$C_p \left[J/kg \cdot K \right] \qquad 383 \qquad 2000$
sp [] /
$k[W/m \cdot K] = 400 = 0.2$
$\beta [K^{-1}]$ 1.67 × 10 ⁻⁵ 1 × 10 ⁻³
$\mu [Pa \cdot s] - 0.0275$
$L\left[kJ/kg\right] - 168$
$T_m[K] - 322$

Assumption: (1) laminar flow, (2) incompressible fluid, (3) constant fluid properties except the density ρ , (4) negligible radiation heat transfer 9/13





Find: Temperature distribution and liquid fraction distribution in the domain.

Governing equations:

Continuity equation:

$$\frac{\partial u_i}{\partial x_i} = 0$$

Momentum equations:

$$\rho \frac{D(u_i)}{Dt} = -\frac{\partial p}{\partial x_i} + \mu \frac{\partial^2 u_i}{\partial x_j \partial x_j} + F_i$$





Energy equation for PCM:

$$\frac{\partial(\rho h)}{\partial t} + \frac{\partial(u_i \rho c_{pf} T_f)}{\partial x_i} = k_f \left(\frac{\partial^2 T_f}{\partial x_i^2}\right)$$
Where *h* is the enthalpy, *T_f* is the PCM temperature, *c_{pf}* is PCM specific heat and *k_f* is fluid thermal conductivity.

Energy equation for the fins:

$$\rho_s c_{ps} \frac{\partial T_s}{\partial t} = k_s \left(\frac{\partial^2 T_s}{\partial x_i^2} \right)$$

where T_s is fin temperature and k_s is fin thermal conductivity 12/13







同舟共济 渡彼岸!

People in the same boat help each other to cross to the other bank, where....